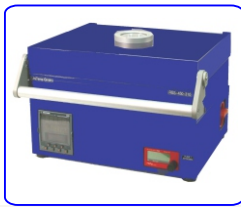
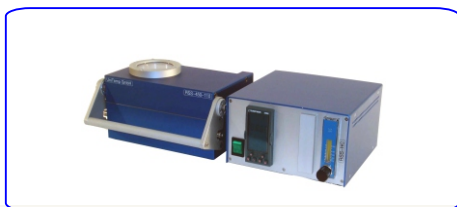


REFLOW SOLDER SYSTEMS AND OVENS

for several reflow solder processes, voidfree, with or without flux,
some models also for contaminating material



Model	RSS-110	RSS-160	RSS-210-S	RSS-310	RSO-200	VSS-450-300
max. substrate size	100 x100mm	160 x160mm	210x210 mm	310x310mm	200x170mm	300x300mm
T _{max}	450 °C	450 °C	450 °C	450 °C	650 °C	450 °C
T °C continuous at	450 °C	450 °C	450 °C	450 °C	650 °C	450 °C
Ramp up rate	120 K/min	100 K/min	180 K/min	100K/min	120K/min	2K/sec
Vacuum up to	10 ⁻³ hPa	10 ⁻³ hPa	10 ⁻³ hPa (*)	10 ⁻³ hPa	10 ⁻³ hPa (*)	10 ⁻³ hPa
Flowmeter	FM analog	FM analog	FM-EL (digital)	FM-EL (digital)	MFC	FM-EL (digital)
Controller	Eurotherm	Eurotherm	Simatic	Eurotherm	Simatic	Eurotherm
(*) optional up to 10 ⁻⁶ hPa						